

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company



N-Channel Silicon MOSFET General-Purpose Switching Device Applications

Features

- ON-resistance $R_{DS}(on)1=33m\Omega$ (typ.)
- 0.9V drive
- Halogen free compliance
- Protection diode in

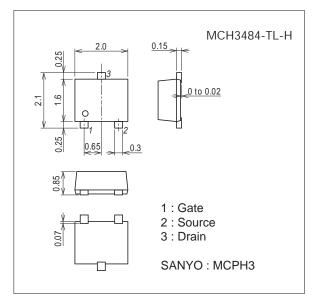
Specifications

Absolute Maximum Ratings at Ta=25°C

-				
Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		20	V
Gate-to-Source Voltage	VGSS		±5	V
Drain Current (DC)	ID		4.5	А
Drain Current (Pulse)	IDP	PW≤10µs, duty cycle≤1%	18	А
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm ² ×0.8mm)	1.0	W
Channel Temperature	Tch		150	°C
Operating Temperature	Topr		-5 to +150	°C
Storage Temperature	Tstg		-55 to +150	°C

Package Dimensions

unit : mm (typ) 7019A-003



Product & Package Information

• Package : MCPH3

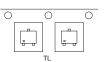
• JEITA, JEDEC

: SC-70, SOT-323

Minimum Packing Quantity : 3,000 pcs./reel

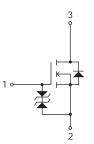
Packing Type : TL

Marking





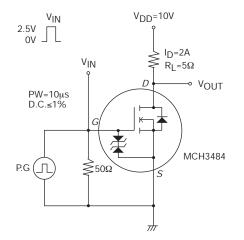
Electrical Connection



Electrical Characteristics at Ta=25°C

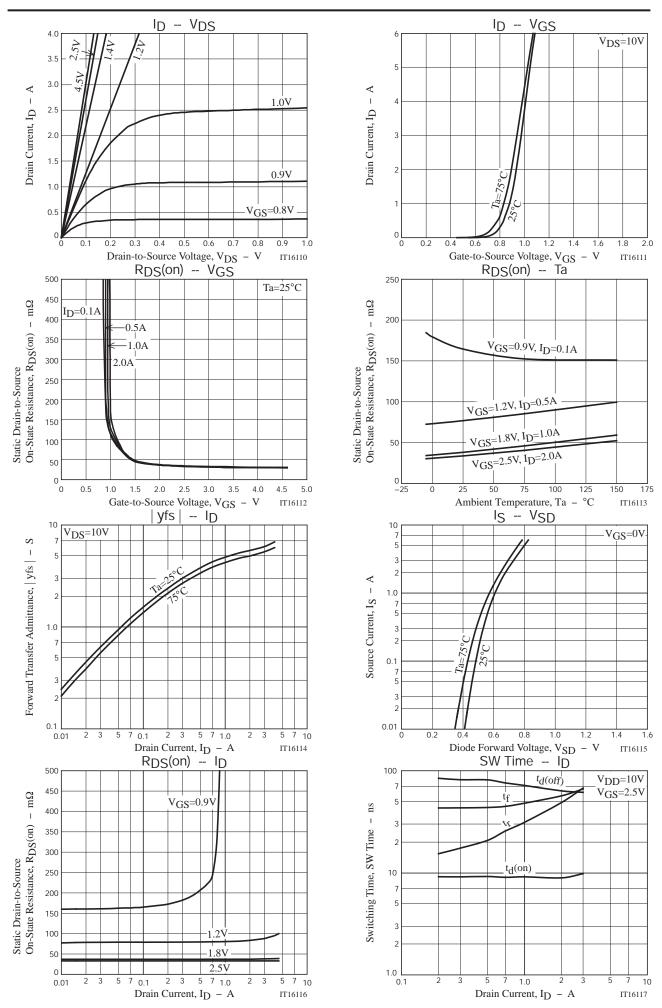
Deservation	Cumpleal	Conditions		Ratings			
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	20			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =20V, V _{GS} =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V _{GS} =±4V, V _{DS} =0V			±10	μΑ	
Cutoff Voltage	V _{GS} (off)	V _{DS} =10V, I _D =1mA	0.3		0.8	V	
Forward Transfer Admittance	yfs	V _{DS} =10V, I _D =2A		5.6		S	
	R _{DS} (on)1	ID=2A, VGS=2.5V		33	40	mΩ	
Statia Drain to Source On State Desistance	R _{DS} (on)2	ID=1A, VGS=1.8V		37	49	mΩ	
Static Drain-to-Source On-State Resistance	R _{DS} (on)3	ID=0.5A, VGS=1.2V		79	119	mΩ	
	RDS(on)4	ID=0.1A, VGS=0.9V		165	330	mΩ	
Input Capacitance	Ciss			630		pF	
Output Capacitance	Coss	V _{DS} =10V, f=1MHz		75		pF	
Reverse Transfer Capacitance	Crss			65		pF	
Turn-ON Delay Time	t _d (on)			8.9		ns	
Rise Time	tr			49		ns	
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit.		63		ns	
Fall Time	tf	7		57		ns	
Total Gate Charge	Qg			11		nC	
Gate-to-Source Charge	Qgs	VDS=10V, VGS=2.5V, ID=4.5A		0.9		nC	
Gate-to-Drain "Miller" Charge	Qgd]		1.8		nC	
Diode Forward Voltage	V _{SD}	IS=4.5A, VGS=0V		0.8	1.2	V	

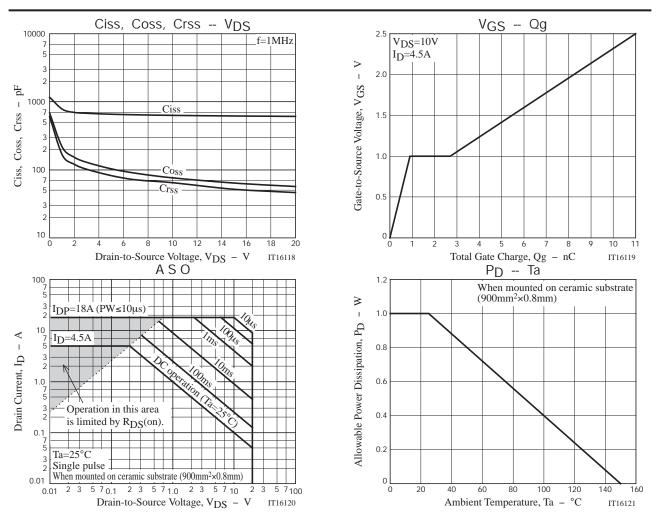
Switching Time Test Circuit



Ordering Information

8					
Device	Device Package		memo		
MCH3484-TL-H	MCPH3	3,000pcs./reel	Pb Free and Halogen Free		





Taping Specification MCH3484-TL-H

1. Packing Format

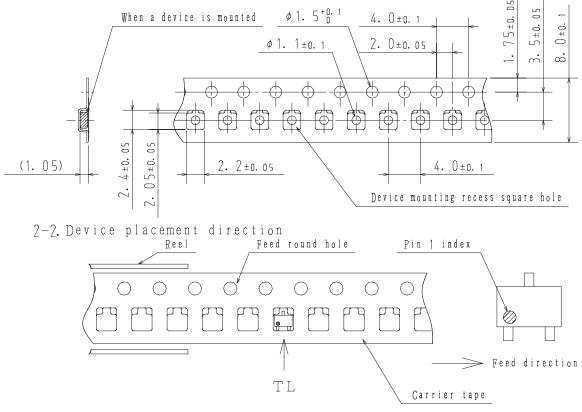
Package Name	Carrier Tape	Maximun Number of devices contained (pcs)			Packing format			
	Туре	Reel	Inner box	Outer box	Inner BOX (C-1)			Outer BOX (A-7)
MCPH3	МСРНЗ	3,000	15,000	90,000	5 reels contained			6 inner boxes contained
					Dime	nsions:mm (external)	Dimensions:mm (external)
					18	$3 \times 72 \times$	185	440×195×210
			Reel	label, I	Inner	box label		box label
Packing met	hod			(u 1	nit:r	nm)	The for	label at the time of factory shipments, m of a label may change in physical ution process.
°			<	(59	>	<	108
	Туре				00000)) 		TYPE CODE
						m		QTY 0,000 PCS LEAD FREE *
	///// Quan	tıty	(Z)	II IIIII IIIIIII Special		AD FREE *		LOT OCCOCCO
	Orig	in	> A:	* Z 0 7 2 2 SSEMBLY:**** (005310 DIFFUSIO	 C* :*****)	. L	
			NOTE	· (1)		i		*2CIAL *20722005310C* \$\$SEMBLY:*****(DIFFUSION:*****)
	∖ Reel la	bel	Th	e LEAD FI				nat the surface
			- tr	eatment	ot the	terminal i	s lead fi	сее,
				Label		JEITA	Phase	
				LEAD FRH	EE 3	JΕΙΤΑ Ρ	hase 3A	

LEAD FREE 4

JEITA Phase 3

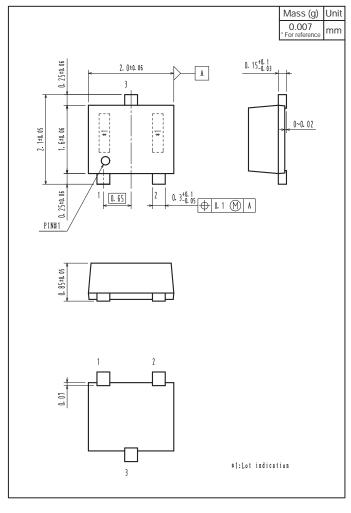
2. Taping configuration

2-1. Carrier tape size (unit:mm)

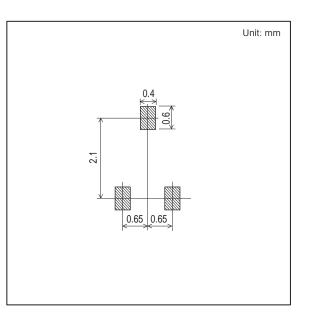


Those with pin 1 index on the feed hole side $\cdots \cdots TL$

Outline Drawing MCH3484-TL-H



Land Pattern Example



Note on usage : Since the MCH3484 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

- Any and all SANYO Semiconductor Co.,Ltd. products described or contained herein are, with regard to "standard application", intended for the use as general electronics equipment. The products mentioned herein shall not be intended for use for any "special application" (medical equipment whose purpose is to sustain life, aerospace instrument, nuclear control device, burning appliances, transportation machine, traffic signal system, safety equipment etc.) that shall require extremely high level of reliability and can directly threaten human lives in case of failure or malfunction of the product or may cause harm to human bodies, nor shall they grant any guarantee thereof. If you should intend to use our products for new introduction or other application different from current conditions on the usage of automotive device, communication device, office equipment, industrial equipment etc. , please consult with us about usage condition (temperature, operation time etc.) prior to the intended use. If there is no consultation or inquiry before the intended use, our customer shall be solely responsible for the use.
- Specifications of any and all SANYO Semiconductor Co.,Ltd. products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- SANYO Semiconductor Co.,Ltd. assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all SANYO Semiconductor Co.,Ltd. products described or contained herein.
- Regarding monolithic semiconductors, if you should intend to use this IC continuously under high temperature, high current, high voltage, or drastic temperature change, even if it is used within the range of absolute maximum ratings or operating conditions, there is a possibility of decrease reliability. Please contact us for a confirmation.
- SANYO Semiconductor Co.,Ltd. strives to supply high-quality high-reliability products, however, any and all semiconductor products fail or malfunction with some probability. It is possible that these probabilistic failures or malfunction could give rise to accidents or events that could endanger human lives, trouble that could give rise to smoke or fire, or accidents that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all SANYO Semiconductor Co.,Ltd. products described or contained herein are controlled under any of applicable local export control laws and regulations, such products may require the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written consent of SANYO Semiconductor Co.,Ltd.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the SANYO Semiconductor Co.,Ltd. product that you intend to use.
- Upon using the technical information or products described herein, neither warranty nor license shall be granted with regard to intellectual property rights or any other rights of SANYO Semiconductor Co.,Ltd. or any third party. SANYO Semiconductor Co.,Ltd. shall not be liable for any claim or suits with regard to a third party's intellectual property rights which has resulted from the use of the technical information and products mentioned above.

This catalog provides information as of May, 2012. Specifications and information herein are subject to change without notice.